




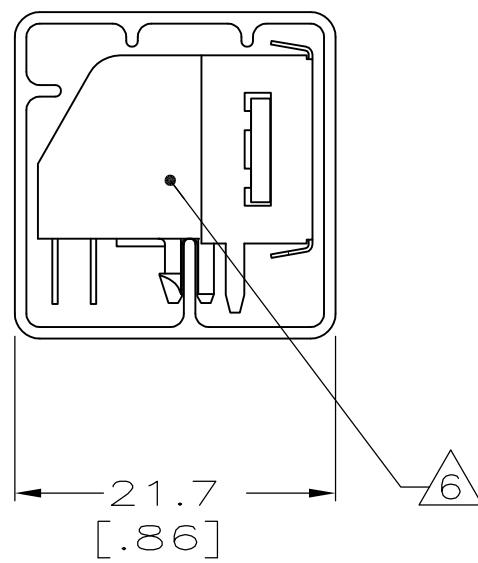
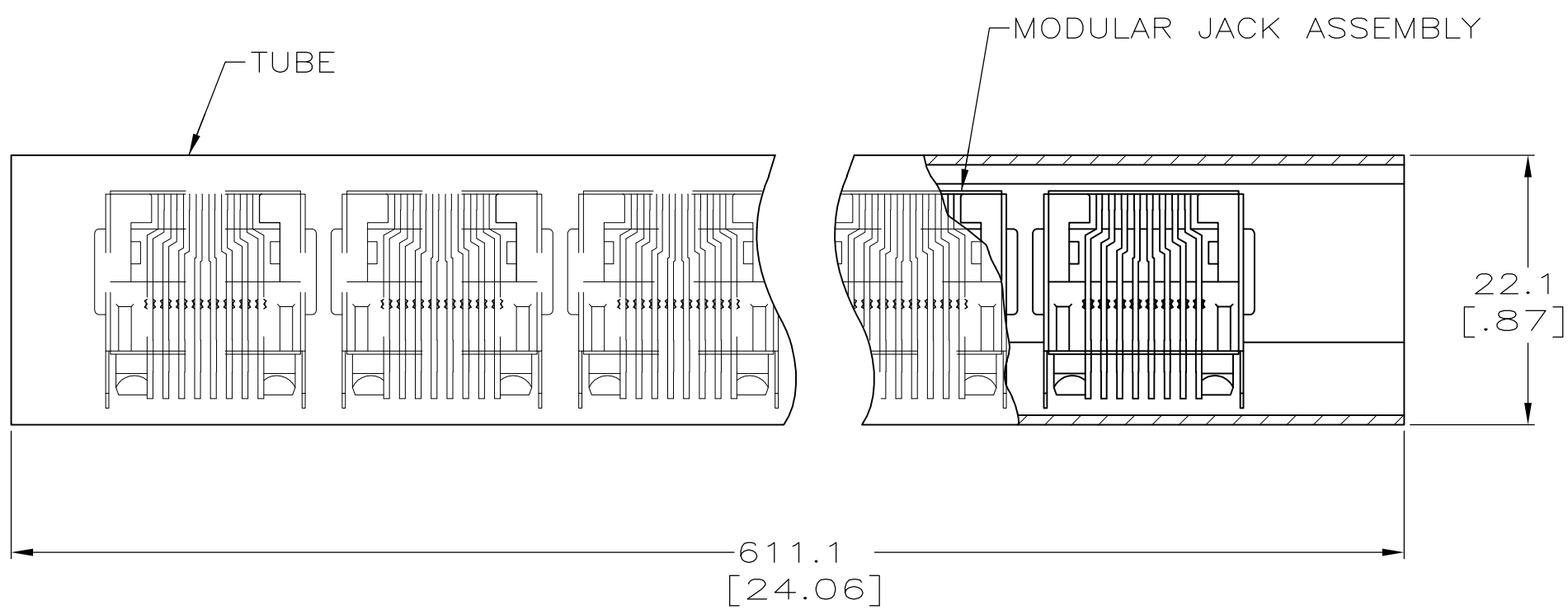
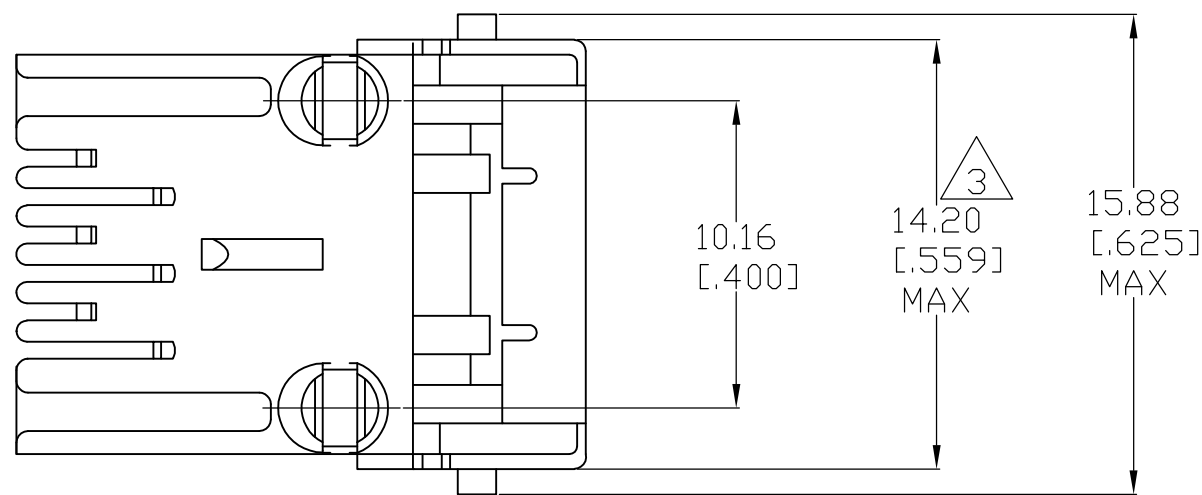
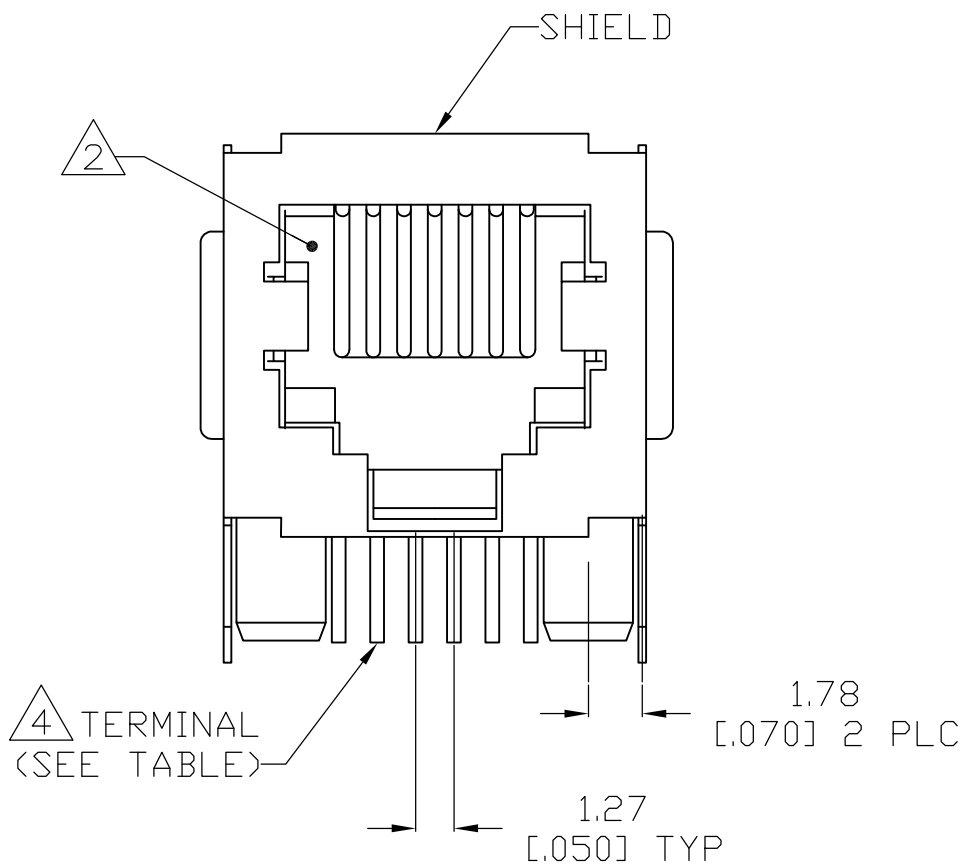
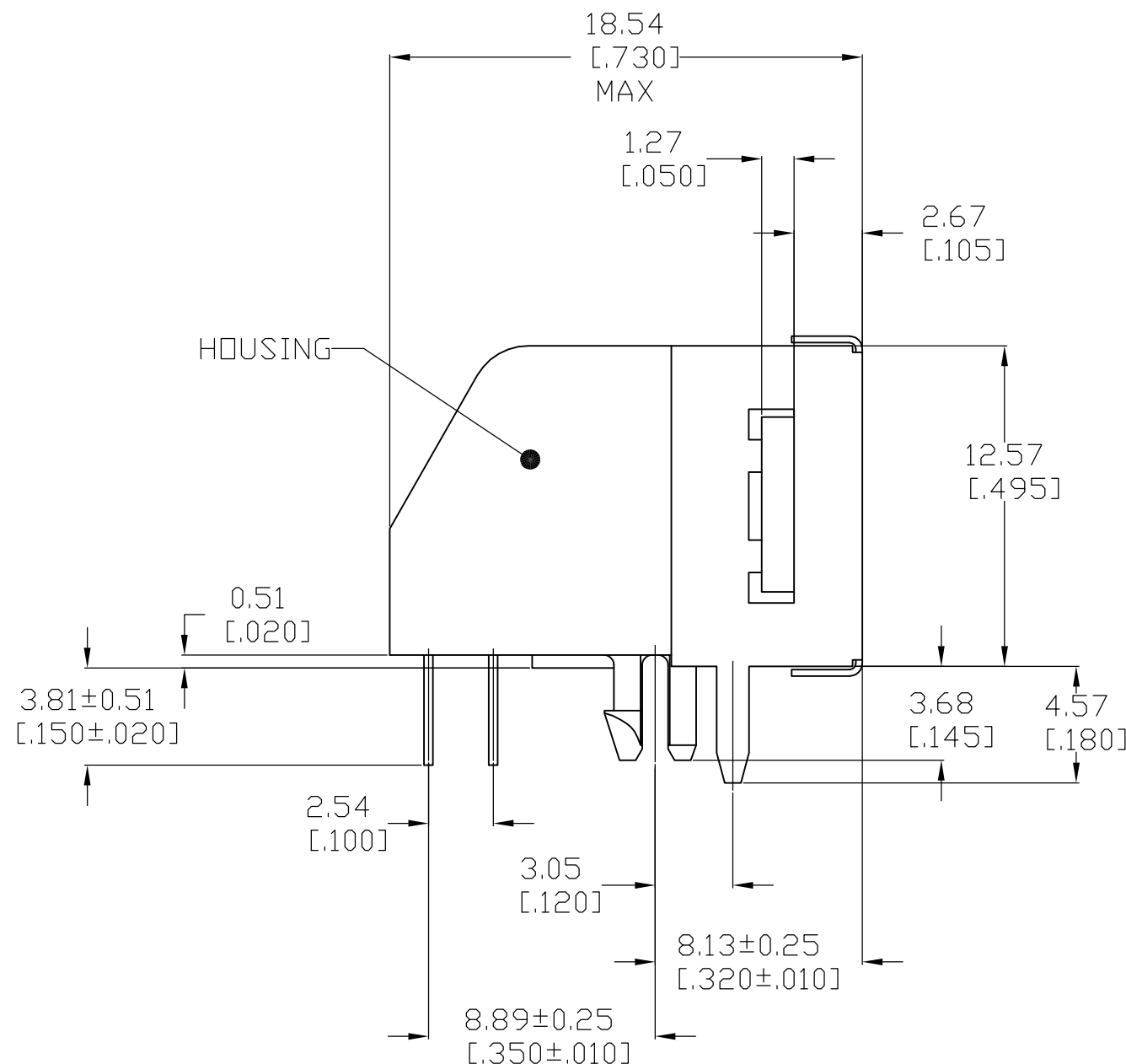


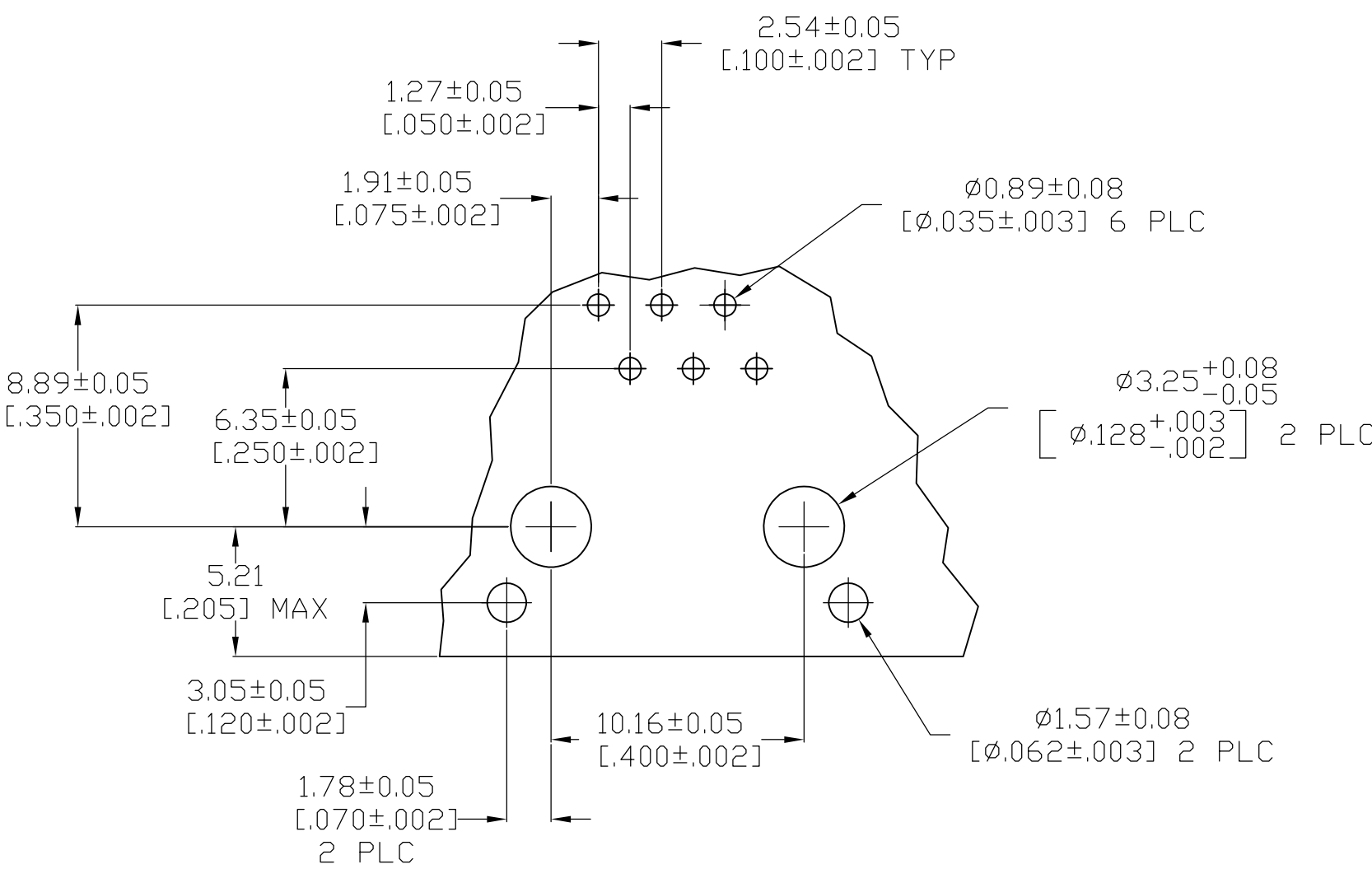
LOC		DIST		REVISIONS				
AA	00	P	LTR	DESCRIPTION		DATE	DWN	APVD
		B1		REVISED PER ECO-11-005033		23MAR11	RK	HMR

1. MATERIAL: HOUSING--PBT POLYESTER, COLOR: BLACK
TERMINAL- 0.36[.014] THICK PHOS-BRONZE PLATED WITH 1.27 μ m[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81 μ m[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27 μ m[.000050] MINIMUM THICK NICKEL UNDERPLATE
SHIELD-0.25[.010] THICK COPPER ALLOY PLATED WITH 3.0 μ m[.000120] MINIMUM REFLOWED TIN

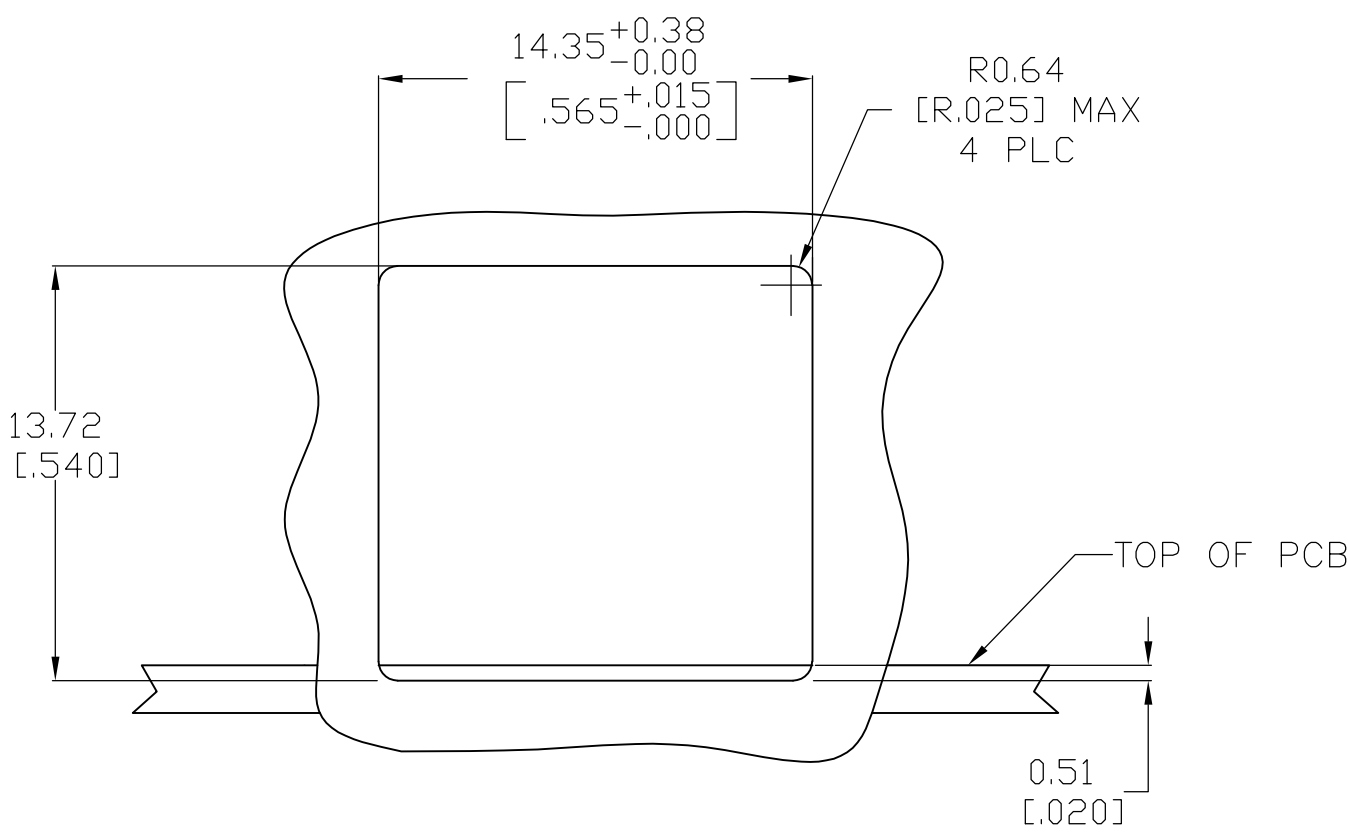
-  CAVITY CONFORMS TO FCC RULES AND REGULATIONS PART 68, SUBPART F.
-  DIMENSION MEASURED ALONG FRONT EDGE OF MATING FACE
-  TERMINALS FOR 5555154-2 LOCATED IN CENTER POSITIONS.
-  BULK PACKAGED IN TRAYS.
-  PACKAGED 36 ASSEMBLIES PER TUBE. SEE DETAIL "A".






DETAIL A
SCALE 2:1





RECOMMENDED PRINTED CIRCUIT BOARD LAYOUT
(COMPONENT SIDE)



RECOMMENDED PANEL CUTOUT

	6	5555154-4
	4	5555154-2
	6	5555154-1
PACKAGE		PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN G. ATTADIA - 08/JUN/2005	 TE Connectivity	
		CHK J. WESTMAN - 08/JUN/2005		
DIMENSIONS: mm [INCHES]		APVD S. FLICKINGER 08/JUN/2005	NAME	
		PRODUCT SPEC 108-1163	MODULAR JACK ASSEMBLY, SHIELDED, 6 POSITION, LOW PROFILE, RIGHT ANGLE, PRINTED CIRCUIT BOARD GROUND WITH PANEL STOPS	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APPLICATION SPEC 114-2048	SIZE	CAGE CODE
0 PLC ± -		WEIGHT	A1	00779
1 PLC ± -			DRAWING NO	
2 PLC ± 0.13[.005]			C=5555154	
3 PLC ± -			RESTRICTED TO	
4 PLC ± -				
ANGLES ± -				
FINISH			SCALE	
SEE NOTE 1			4:1	
MATERIAL			SHEET	
			1 OF	
			REV	
			B	

Mouser Electronics

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Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[TE Connectivity:](#)

[5555154-1](#)